

# CMOS Dual 4-Stage Static Shift Register

With Serial Input/Parallel Output

High-Voltage Types (20-Volt Rating)

■ CD4015B consists of two identical, independent, 4-stage serial-input/parallel-output registers. Each register has independent CLOCK and RESET inputs as well as a single serial DATA input. "Q" outputs are available from each of the four stages on both registers. All register stages are D-type, master-slave flip-flops. The logic level present at the DATA input is transferred into the first register stage and shifted over one stage at each positive-going clock transition. Resetting of all stages is accomplished by a high level on the reset line. Register expansion to 8 stages using one CD4015B package, or to more than 8 stages using additional CD4015B's is possible.

The CD4015B-series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic package (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

## Features:

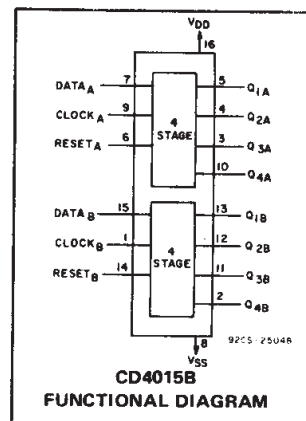
- Medium speed operation . . . . .  
12 MHz (typ.) clock rate at  $V_{DD} - V_{SS} = 10\text{ V}$
- Fully static operation
- 8 master-slave flip-flops plus input and output buffering
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized, symmetrical output characteristics
- Maximum input current of  $1\text{ }\mu\text{A}$  at 18 V over full package-temperature range;  
100 nA at 18 V and  $25^\circ\text{C}$
- Noise margin (full package-temperature range) =  
1 V at  $V_{DD} = 5\text{ V}$   
2 V at  $V_{DD} = 10\text{ V}$   
2.5 V at  $V_{DD} = 15\text{ V}$

- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

## Applications:

- Serial-input/parallel-output data queueing
- Serial to parallel data conversion
- General-purpose register

# CD4015B Types



TERMINAL DIAGRAM

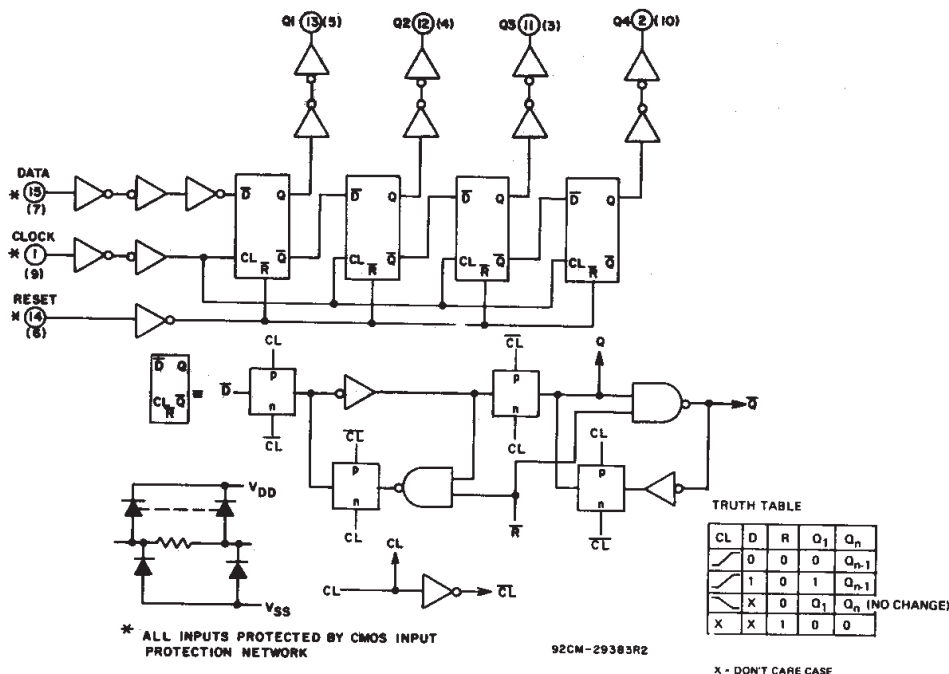
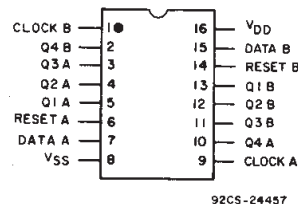


Fig. 1 – Logic diagram (1 register).

# CD4015B Types

## MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )

Voltages referenced to  $V_{SS}$  Terminal)

-0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS

-0.5V to  $V_{DD} + 0.5V$

DC INPUT CURRENT, ANY ONE INPUT

$\pm 10mA$

POWER DISSIPATION PER PACKAGE ( $P_D$ ):

For  $T_A = -55^\circ C$  to  $+100^\circ C$

500mW

For  $T_A = +100^\circ C$  to  $+125^\circ C$

Derate Linearity at 12mW/ $^\circ C$  to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR  $T_A =$  FULL PACKAGE-TEMPERATURE RANGE (All Package Types)

100mW

OPERATING-TEMPERATURE RANGE ( $T_A$ )

$-55^\circ C$  to  $+125^\circ C$

STORAGE TEMPERATURE RANGE ( $T_{stg}$ )

$-65^\circ C$  to  $+150^\circ C$

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16  $\pm$  1/32 inch (1.59  $\pm$  0.79mm) from case for 10s max  $+265^\circ C$

RECOMMENDED OPERATING CONDITIONS at  $T_A = 25^\circ C$ , Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

| CHARACTERISTIC                                                    | $V_{DD}$<br>(V) | LIMITS |      | UNITS   |
|-------------------------------------------------------------------|-----------------|--------|------|---------|
|                                                                   |                 | Min.   | Max. |         |
| Supply-Voltage Range (For $T_A =$ Full Package-Temperature Range) |                 | 3      | 18   | V       |
| Clock Pulse Width, $t_{WCL}$                                      | 5               | 180    | —    | ns      |
|                                                                   | 10              | 80     | —    |         |
|                                                                   | 15              | 50     | —    |         |
| Clock Rise and Fall Time, $t_{rCL}, t_{fCL}$                      | 5               | —      | 15   | $\mu s$ |
|                                                                   | 10              | —      | 6    |         |
|                                                                   | 15              | —      | 2    |         |
| Clock Input Frequency, $f_{CL}$                                   | 5               | —      | 3    | MHz     |
|                                                                   | 10              | DC     | 6    |         |
|                                                                   | 15              | —      | 8.5  |         |
| Data Setup Time, $t_{SU}$                                         | 5               | 70     | —    | ns      |
|                                                                   | 10              | 40     | —    |         |
|                                                                   | 15              | 30     | —    |         |
| Reset Pulse Width, $t_{WR}$                                       | 5               | 200    | —    | ns      |
|                                                                   | 10              | 80     | —    |         |
|                                                                   | 15              | 60     | —    |         |

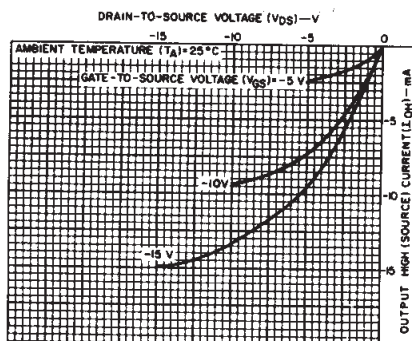


Fig. 5 — Minimum output high (source) current characteristics.

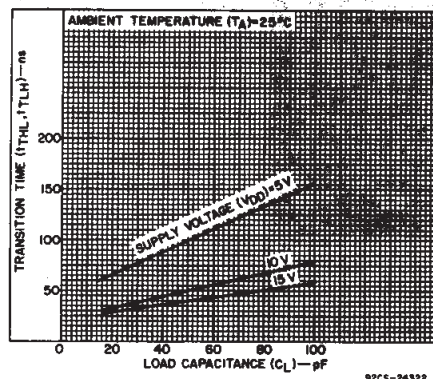


Fig. 6 — Typical transition time as a function of load capacitance.

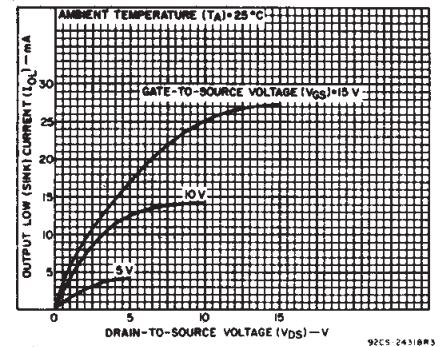


Fig. 2 — Typical output low (sink) current characteristics.

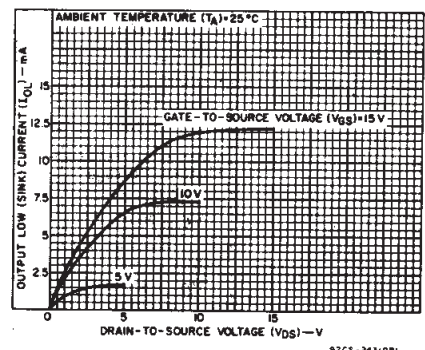


Fig. 3 — Minimum output low (sink) current characteristics.

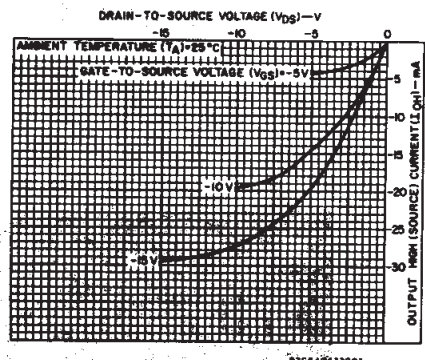


Fig. 4 — Typical output high (source) current characteristics.

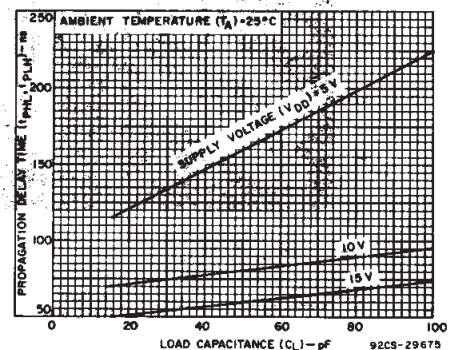


Fig. 7 — Typical propagation delay time as a function of load capacitance.

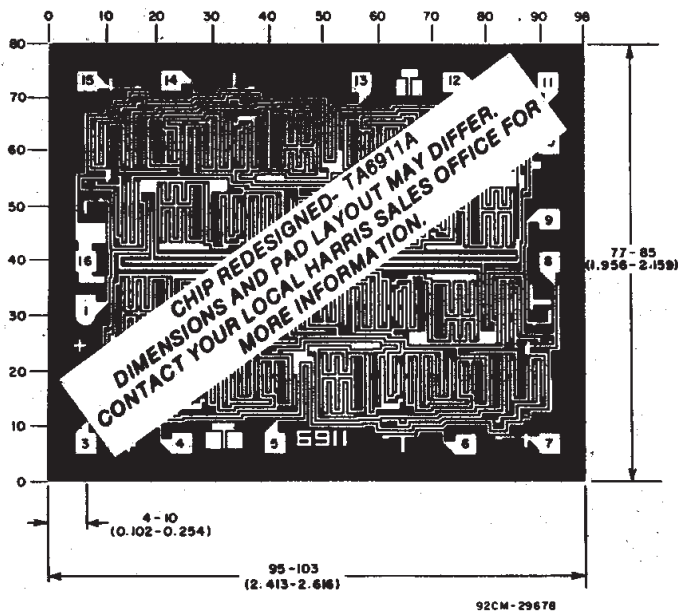
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COMMERCIAL CMOS  
HIGH VOLTAGE ICs

## CD4015B Types

### STATIC ELECTRICAL CHARACTERISTICS

| CHARACTER-<br>ISTIC                                         | CONDITIONS            |                        |                        | LIMITS AT INDICATED TEMPERATURES (°C) |       |       |       |       |                   |      | UNITS |
|-------------------------------------------------------------|-----------------------|------------------------|------------------------|---------------------------------------|-------|-------|-------|-------|-------------------|------|-------|
|                                                             | V <sub>O</sub><br>(V) | V <sub>IN</sub><br>(V) | V <sub>DD</sub><br>(V) |                                       |       |       |       | +25   |                   |      |       |
|                                                             |                       |                        |                        | -55                                   | -40   | +85   | +125  | Min.  | Typ.              | Max. |       |
| Quiescent Device<br>Current,<br>I <sub>DD</sub> Max.        | —                     | 0,5                    | 5                      | 5                                     | 5     | 150   | 150   | —     | 0.04              | 5    | μA    |
|                                                             | —                     | 0,10                   | 10                     | 10                                    | 10    | 300   | 300   | —     | 0.04              | 10   |       |
|                                                             | —                     | 0,15                   | 15                     | 20                                    | 20    | 600   | 600   | —     | 0.04              | 20   |       |
|                                                             | —                     | 0,20                   | 20                     | 100                                   | 100   | 3000  | 3000  | —     | 0.08              | 100  |       |
| Output Low<br>(Sink) Current<br>I <sub>OL</sub> Min.        | 0.4                   | 0,5                    | 5                      | 0.64                                  | 0.61  | 0.42  | 0.36  | 0.51  | 1                 | —    | mA    |
|                                                             | 0.5                   | 0,10                   | 10                     | 1.6                                   | 1.5   | 1.1   | 0.9   | 1.3   | 2.6               | —    |       |
|                                                             | 1.5                   | 0,15                   | 15                     | 4.2                                   | 4     | 2.8   | 2.4   | 3.4   | 6.8               | —    |       |
| Output High<br>(Source)<br>Current,<br>I <sub>OH</sub> Min. | 4.6                   | 0,5                    | 5                      | -0.64                                 | -0.61 | -0.42 | -0.36 | -0.51 | -1                | —    | mA    |
|                                                             | 2.5                   | 0,5                    | 5                      | -2                                    | -1.8  | -1.3  | -1.15 | -1.6  | -3.2              | —    |       |
|                                                             | 9.5                   | 0,10                   | 10                     | -1.6                                  | -1.5  | -1.1  | -0.9  | -1.3  | -2.6              | —    |       |
|                                                             | 13.5                  | 0,15                   | 15                     | -4.2                                  | -4    | -2.8  | -2.4  | -3.4  | -6.8              | —    |       |
| Output Voltage:<br>Low-Level,<br>V <sub>OL</sub> Max.       | —                     | 0,5                    | 5                      | 0.05                                  |       |       |       | —     | 0                 | 0.05 | V     |
|                                                             | —                     | 0,10                   | 10                     | 0.05                                  |       |       |       | —     | 0                 | 0.05 |       |
|                                                             | —                     | 0,15                   | 15                     | 0.05                                  |       |       |       | —     | 0                 | 0.05 |       |
| Output Voltage:<br>High-Level,<br>V <sub>OH</sub> Min.      | —                     | 0,5                    | 5                      | 4.95                                  |       |       |       | 4.95  | 5                 | —    | V     |
|                                                             | —                     | 0,10                   | 10                     | 9.95                                  |       |       |       | 9.95  | 10                | —    |       |
|                                                             | —                     | 0,15                   | 15                     | 14.95                                 |       |       |       | 14.95 | 15                | —    |       |
| Input Low<br>Voltage,<br>V <sub>IL</sub> Max.               | 0.5, 4.5              | —                      | 5                      | 1.5                                   |       |       |       | —     | —                 | 1.5  | V     |
|                                                             | 1, 9                  | —                      | 10                     | 3                                     |       |       |       | —     | —                 | 3    |       |
|                                                             | 1.5,13.5              | —                      | 15                     | 4                                     |       |       |       | —     | —                 | 4    |       |
| Input High<br>Voltage,<br>V <sub>IH</sub> Min.              | 0.5, 4.5              | —                      | 5                      | 3.5                                   |       |       |       | 3.5   | —                 | —    | V     |
|                                                             | 1, 9                  | —                      | 10                     | 7                                     |       |       |       | 7     | —                 | —    |       |
|                                                             | 1.5,13.5              | —                      | 15                     | 11                                    |       |       |       | 11    | —                 | —    |       |
| Input Current<br>I <sub>IN</sub> Max.                       | —                     | 0,18                   | 18                     | ±0.1                                  | ±0.1  | ±1    | ±1    | —     | ±10 <sup>-5</sup> | ±0.1 | μA    |



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).

Photograph of Chip Layout for CD4015B.

## CD4015B Types

**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20\text{ ns}$ ,  
 $C_L = 50\text{ pF}$ ,  $R_L = 200\text{ k}\Omega$

| CHARACTERISTIC                                                     | TEST CONDITIONS<br>V <sub>DD</sub> (V) | LIMITS |      |      | UNITS |
|--------------------------------------------------------------------|----------------------------------------|--------|------|------|-------|
|                                                                    |                                        | MIN.   | TYP. | MAX. |       |
| CLOCKED OPERATION                                                  |                                        |        |      |      |       |
| Propagation Delay Time,<br>T <sub>PHL</sub> , T <sub>PLH</sub>     | 5                                      | —      | 160  | 320  | ns    |
|                                                                    | 10                                     | —      | 80   | 160  |       |
|                                                                    | 15                                     | —      | 60   | 120  |       |
| Transition Time, t <sub>THL</sub> , t <sub>TLH</sub>               | 5                                      | —      | 100  | 200  |       |
|                                                                    | 10                                     | —      | 50   | 100  |       |
|                                                                    | 15                                     | —      | 40   | 80   |       |
| Minimum Clock Pulse<br>Width, t <sub>wCL</sub>                     | 5                                      | —      | 90   | 180  |       |
|                                                                    | 10                                     | —      | 40   | 80   |       |
|                                                                    | 15                                     | —      | 25   | 50   |       |
| Clock Rise and Fall Time,<br>t <sub>rCL</sub> , t <sub>fCL</sub> * | 5                                      | —      | —    | 15   | μs    |
|                                                                    | 10                                     | —      | —    | 6    |       |
|                                                                    | 15                                     | —      | —    | 2    |       |
| Minimum Data Setup Time,<br>t <sub>SU</sub>                        | 5                                      | —      | 35   | 70   | ns    |
|                                                                    | 10                                     | —      | 20   | 40   |       |
|                                                                    | 15                                     | —      | 15   | 30   |       |
| Minimum Data Hold Time, t <sub>H</sub>                             | 5                                      | —      | —    | 0    |       |
|                                                                    | 10                                     | —      | —    | 0    |       |
|                                                                    | 15                                     | —      | —    | 0    |       |
| Maximum Clock Input<br>Frequency, f <sub>CL</sub>                  | 5                                      | 3      | 6    | —    | MHz   |
|                                                                    | 10                                     | 6      | 12   | —    |       |
|                                                                    | 15                                     | 8.5    | 17   | —    |       |
| Input Capacitance, C <sub>IN</sub>                                 | Any Input                              | —      | 5    | 7.5  | pF    |
| RESET OPERATION                                                    |                                        |        |      |      |       |
| Propagation Delay Time,<br>T <sub>PHL</sub> , T <sub>PLH</sub>     | 5                                      | —      | 200  | 400  | ns    |
|                                                                    | 10                                     | —      | 100  | 200  |       |
|                                                                    | 15                                     | —      | 80   | 160  |       |
| Minimum Reset Pulse Width,<br>t <sub>wR</sub>                      | 5                                      | —      | 100  | 200  |       |
|                                                                    | 10                                     | —      | 40   | 80   |       |
|                                                                    | 15                                     | —      | 30   | 60   |       |

\*If more than one unit is cascaded  $t_{rCL}$  should be made less than or equal to the sum of the transition time and the fixed propagation delay of the output of the driving stage for the estimated capacitive load.

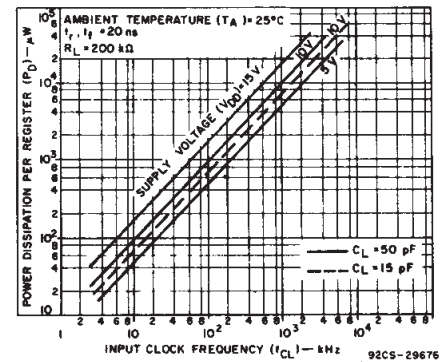


Fig. 8 — Typical power dissipation as a function of frequency.

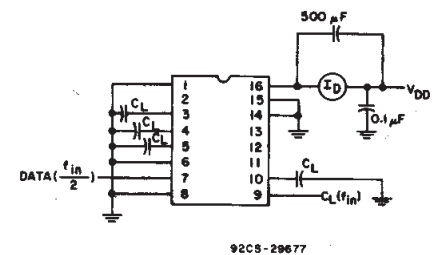


Fig. 9 — Power dissipation test circuit.

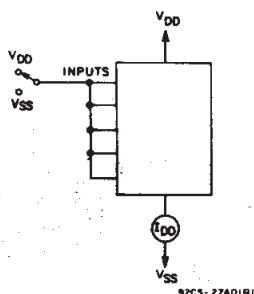


Fig. 10 — Quiescent device current test circuit.

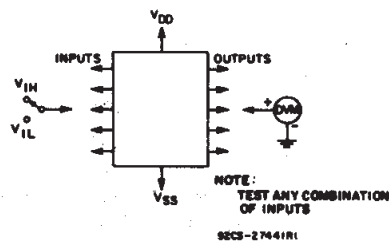


Fig. 11 — Input voltage test circuit.

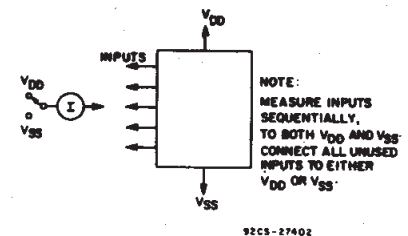


Fig. 12 — Input current test circuit.

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD4015BE         | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| CD4015BEE4       | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| CD4015BF         | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| CD4015BF3A       | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                     | A42              | N / A for Pkg Type           |
| CD4015BM         | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BM96       | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BM96E4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BM96G4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BME4       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BMG4       | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BMT        | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BMTE4      | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BMTG4      | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BPW        | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BPWE4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BPWG4      | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BPWR       | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BPWRE4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| CD4015BPWRG4     | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

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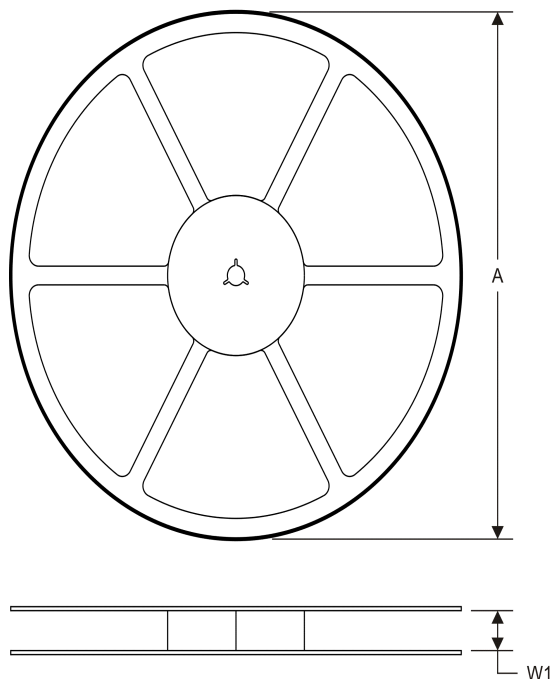
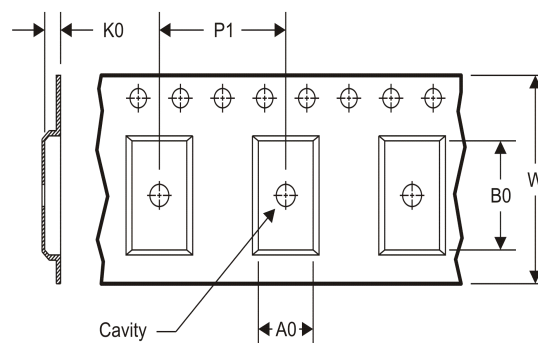
package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |                                                           |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

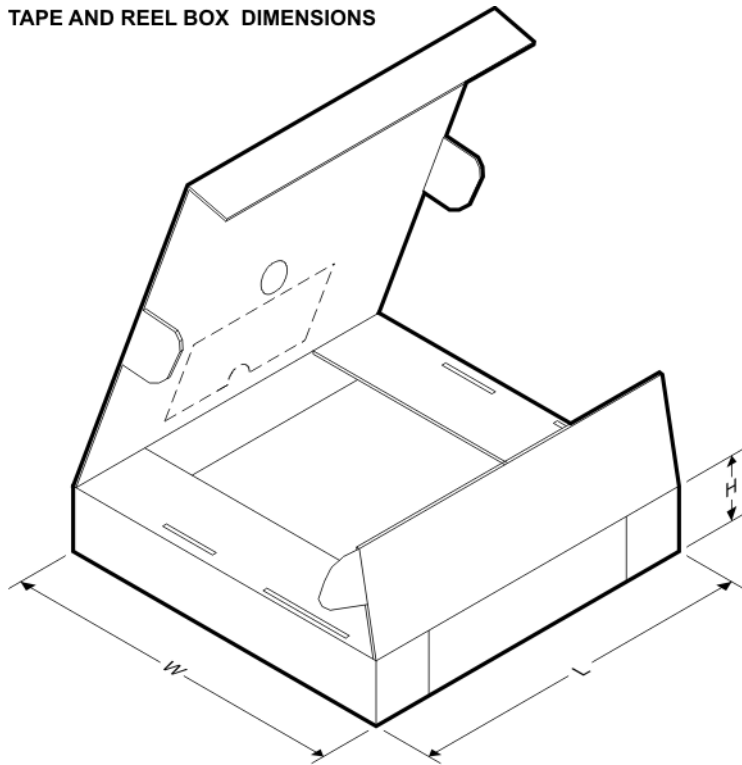
**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device     | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4015BM96 | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| CD4015BPWR | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |



## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

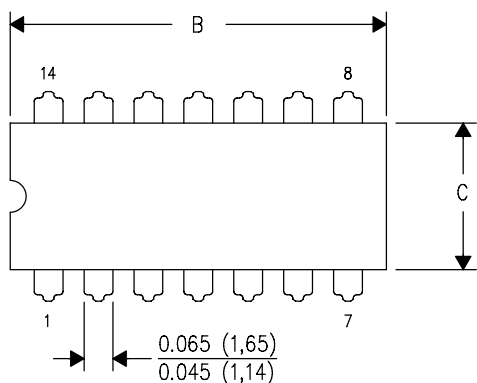
| Device     | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4015BM96 | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| CD4015BPWR | TSSOP        | PW              | 16   | 2000 | 367.0       | 367.0      | 35.0        |



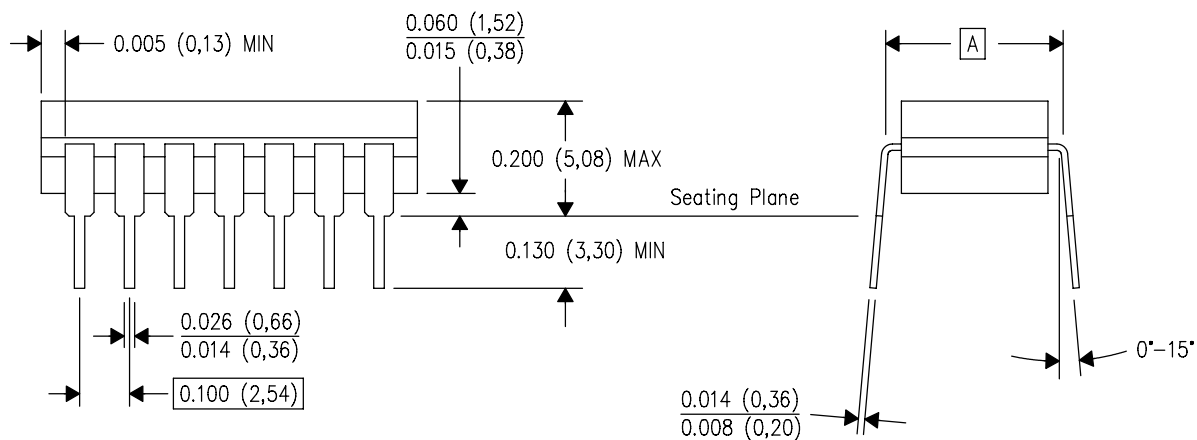
J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



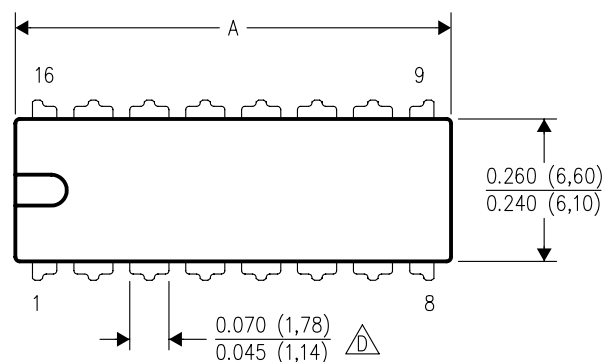
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

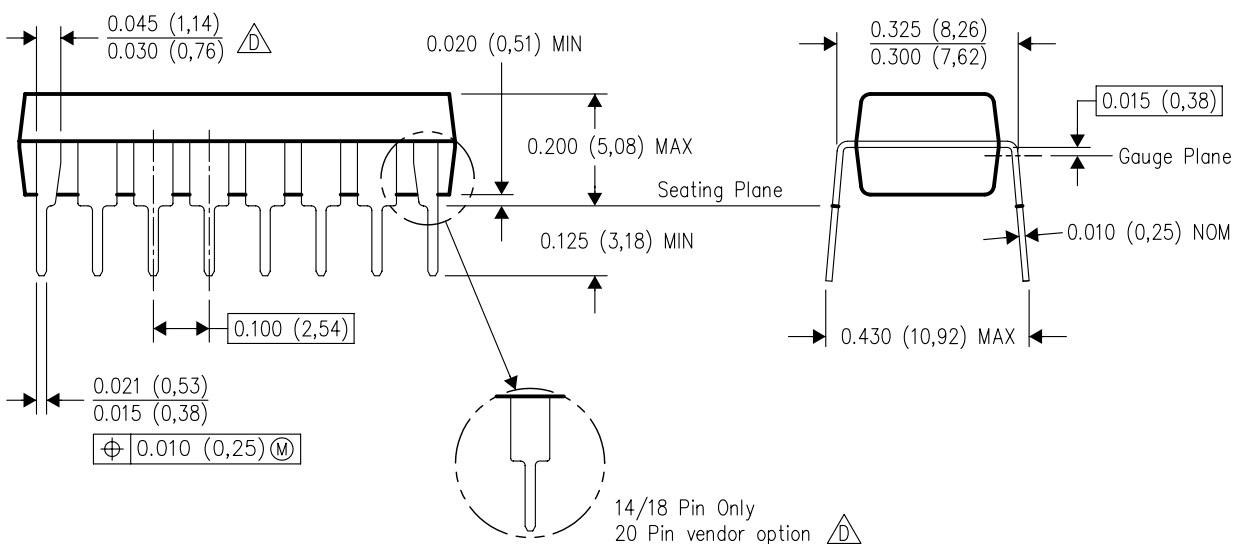
N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |

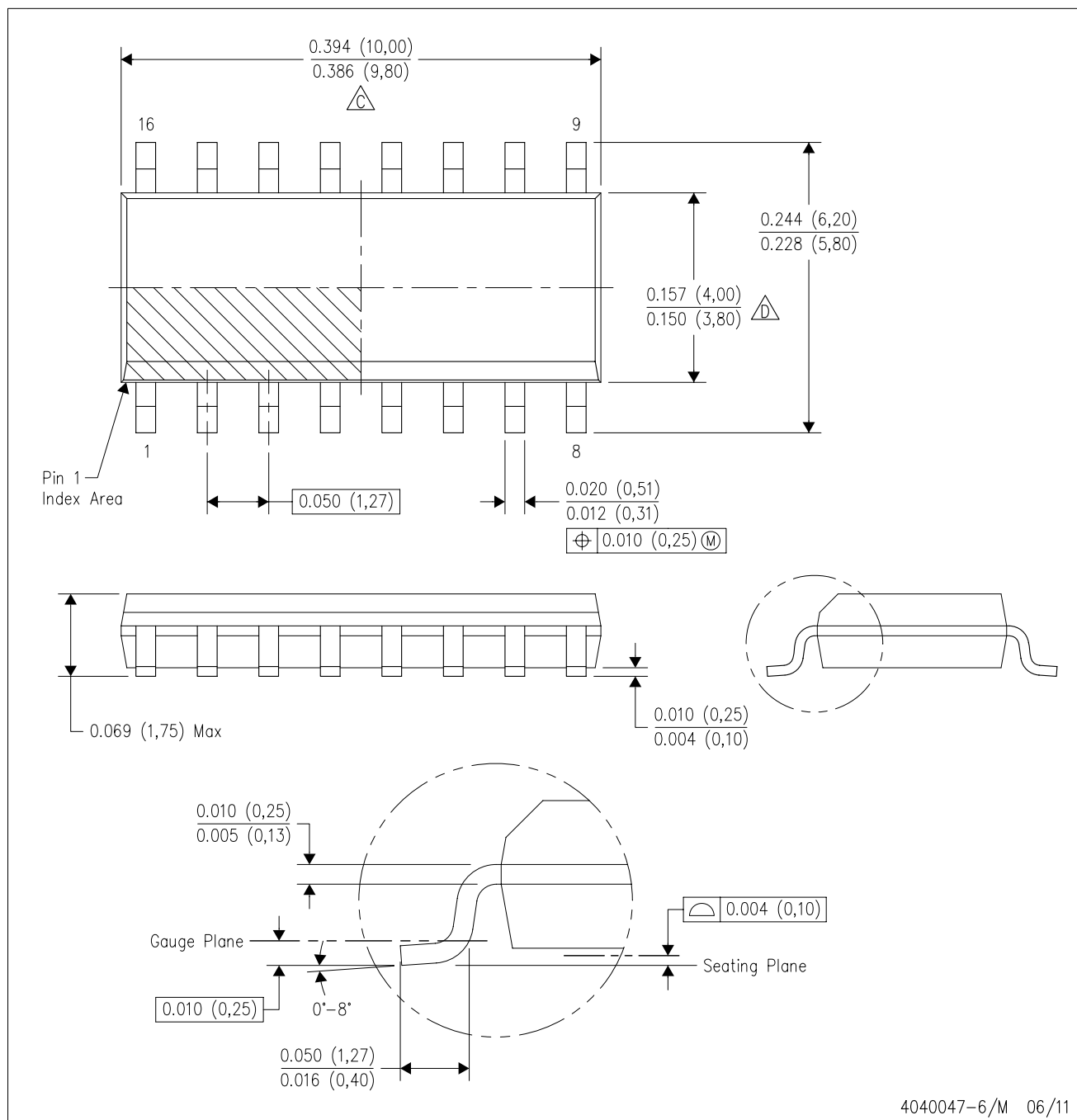


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

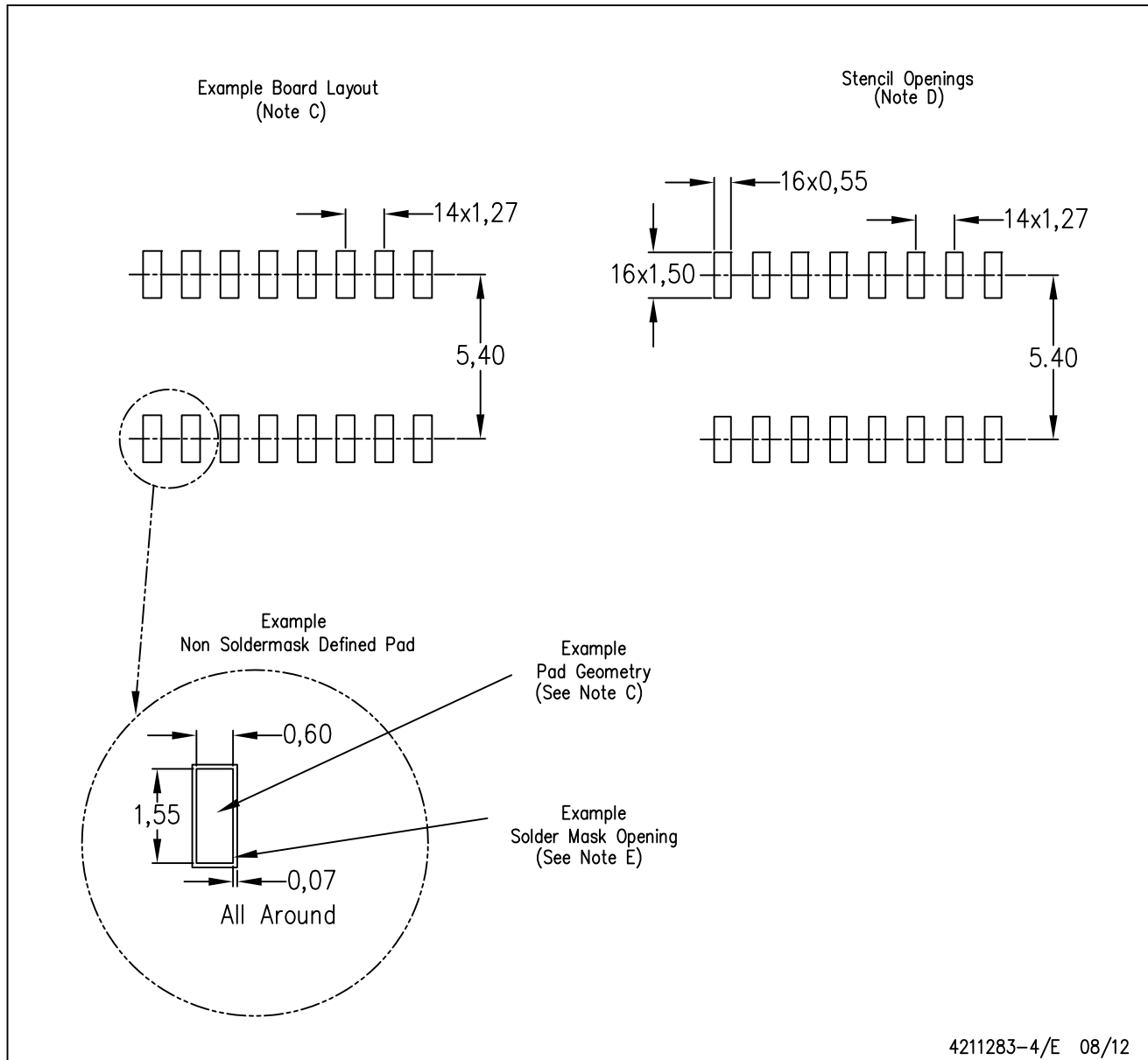


4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

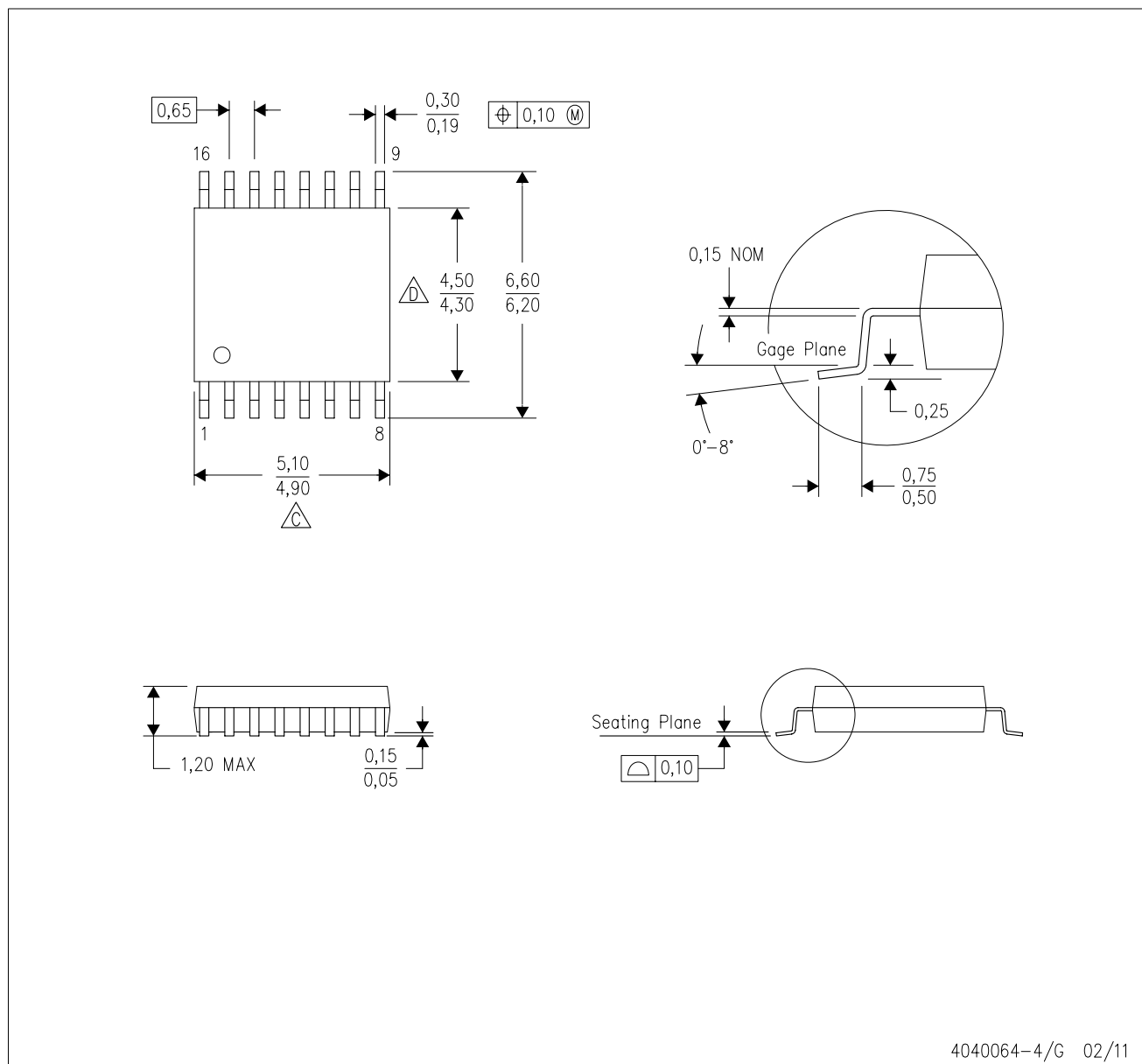
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

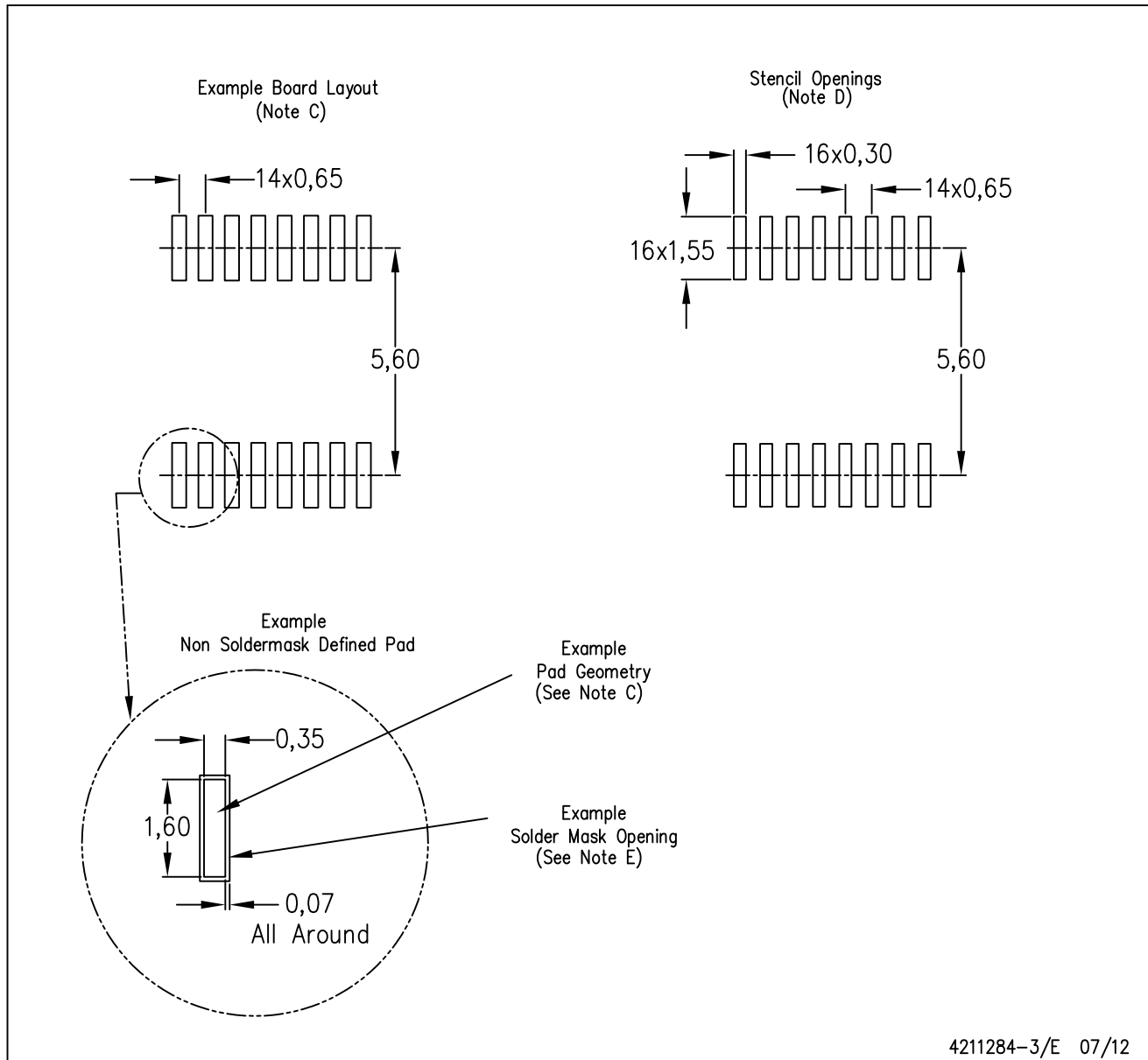


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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| RFID                         | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>                                 |
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|                               |                                                                                          |
|-------------------------------|------------------------------------------------------------------------------------------|
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